ON Semiconductor®

Final Product/Process Change Notification

Document # : FPCN21248XF
Issue Date: 10 February 2017

Title of Change:	Qualification of Amkor Technology Malaysia (ATM) for the Assembly and Test of Trench MOSFET products packaged in SO8FL.
Proposed first ship date:	17 May 2017 or earlier after customer approval
Contact information:	Contact your local ON Semiconductor Sales Office or <GuoKun.Yeng@onsemi.com>
Samples:	Contact your local ON Semiconductor Sales Office or <Amit.Gole@onsemi.com>
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or <Phine.Guevarra@onsemi.com>
Type of notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <PCN.Support@onsemi.com>.
Change Part Identification:	Product from Amkor Technology Malaysia will be marked with site code YE prior to date code.
Change category:	☐ Wafer Fab Change ☒ Assembly Change ☒ Test Change ☐ Other _____

Change Sub-Category(s):

☒ Manufacturing Site Change/Addition
☐ Manufacturing Process Change
☐ Material Change
☐ Product specific change
☐ Datasheet/Product Doc change
☐ Shipping/Packaging/Marking
☐ Other: _____

Sites Affected:

☐ All site(s) ☐ not applicable ☐ ON Semiconductor site(s) :
☒ External Foundry/Subcon site(s)
Amkor Technology Malaysia

Description and Purpose:

This Product Change Notice is to announce that ON Semiconductor is expanding assembly and test operations of SO8FL discrete packaged products, currently built at ON Semiconductor Seremban, Malaysia facility to Amkor Technology Malaysia (ATM).

Upon the expiration of this FPCN or earlier after customer approval, Trench Mosfet devices may be processed at either location. These products have been qualified to commodity/commercial requirements. These products will continue being Pb-free, Halide free and RoHS compliant. Device quality and reliability will continue to meet ON Semiconductors high standards.

Reliability Data Summary:

Test	Specification	Condition	Interval	Results
HTRB	JESD22-A108	Ta=150°C, 80% max rated V	1008 hrs	0/ 252
HTGB	JESD22-A108	Ta=150°C, 100% max rated Vgss	1008 hrs	0/252
HTSL	JESD22-A103	Ta= 150°C	1008 hrs	0/252
IOL	MIL-STD-750 (M1037) AEC-Q101	Ta=+25°C, delta Tj=100°C On/off = 2 min	15000 cyc	0/252
TC	JESD22-A104	Ta= -65°C to +150°C	1000 cyc	0/252
HAST	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs	0/252
uHAST	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs	0/240
PC	J-STD-020 JESD-A113	MSL 1 @ 260 °C		Pass
RSH	JESD22- B106	Ta = 265°C, 10 sec		0/90
SD	JSTD002	Ta = 245°C, 10 sec		0/45

Electrical Characteristic Summary:

There is no change in electrical parametric performance.

List of affected Standard Parts:

Part Number	Qualification Vehicle
NTMFS4C09NT1G	NTMFS4C05NT1G